



# PMBT2907A

60V, 600 mA, PNP switching transistor

6 March 2015

Product data sheet

## 1. General description

PNP switching transistor in a small SOT23 (TO-236AB) Surface-Mounted Device (SMD) plastic package.

NPN complement: PMBT2222A

40V variant: PMBT2907

## 2. Features and benefits

- Single general-purpose switching transistor
- AEC-Q101 qualified

## 3. Applications

- Switching and linear amplification

## 4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{CE0}$	collector-emitter voltage	open base	-	-	-60	V
$I_C$	collector current		-	-	-600	mA
$h_{FE}$	DC current gain	$V_{CE} = -10$ V; $I_C = -150$ mA; $T_{amb} = 25$ °C	100	-	300	

## 5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	B	base	<p>TO-236AB (SOT23)</p>	<p>sym132</p>
2	E	emitter		
3	C	collector		



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## 6. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
PMBT2907A	TO-236AB	plastic surface-mounted package; 3 leads	SOT23

## 7. Marking

Table 4. Marking codes

Type number	Marking code <a href="#">[1]</a>
PMBT2907A	%2F

[1] % = placeholder for manufacturing site code

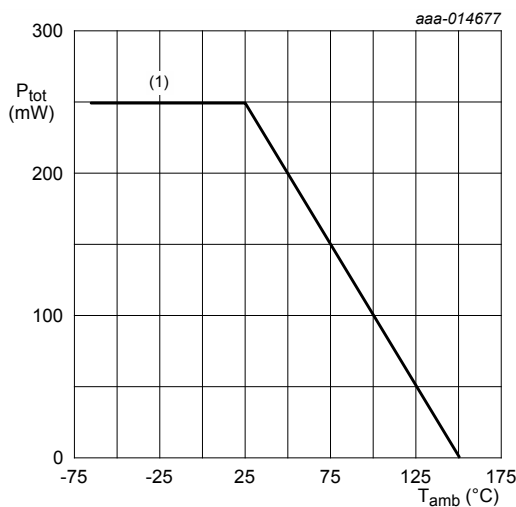
## 8. Limiting values

**Table 5. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
$V_{CBO}$	collector-base voltage	open emitter		-	-60	V
$V_{CEO}$	collector-emitter voltage	open base		-	-60	V
$V_{EBO}$	emitter-base voltage	open collector		-	-5	V
$I_C$	collector current			-	-600	mA
$I_{CM}$	peak collector current	single pulse; $t_p \leq 1$ ms		-	-800	mA
$I_{BM}$	peak base current			-	-200	mA
$P_{tot}$	total power dissipation	$T_{amb} \leq 25$ °C	[1]	-	250	mW
$T_j$	junction temperature			-	150	°C
$T_{amb}$	ambient temperature			-65	150	°C
$T_{stg}$	storage temperature			-65	150	°C

[1] Transistor mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.



(1) FR4 PCB; standard footprint

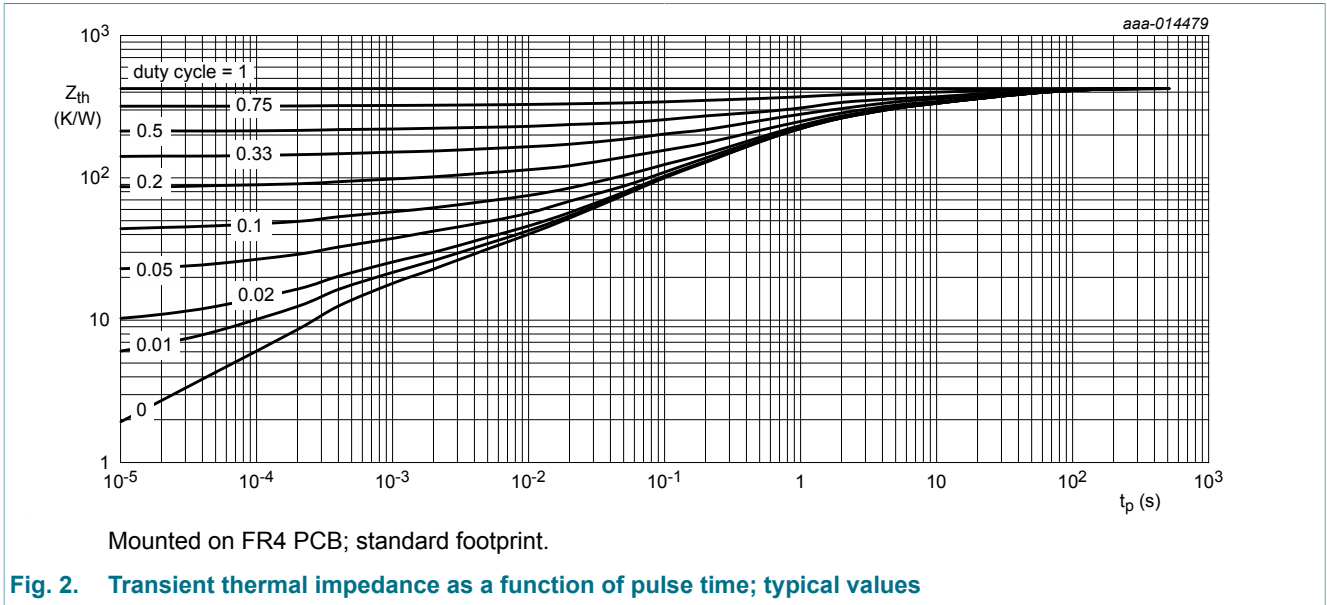
**Fig. 1. Power derating curve**

## 9. Thermal characteristics

**Table 6. Thermal characteristics**

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1]	-	-	500	K/W

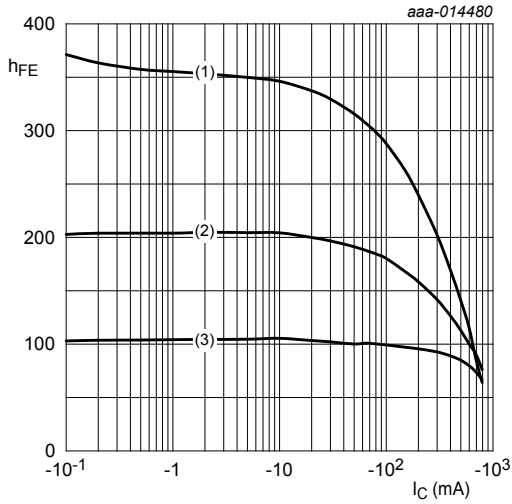
[1] Transistor mounted on an FR4 printed-circuit board, single-sided copper, tin-plated and standard footprint.



## 10. Characteristics

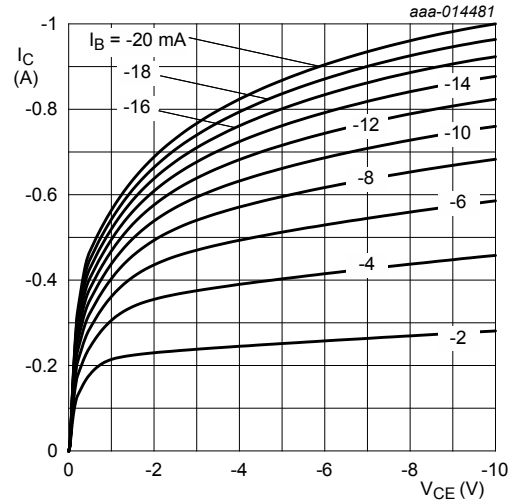
Table 7. Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
I <sub>CBO</sub>	collector-base cut-off current	V <sub>CB</sub> = -50 V; I <sub>E</sub> = 0 A; T <sub>amb</sub> = 25 °C	-	-	-10	nA
		V <sub>CB</sub> = -50 V; I <sub>E</sub> = 0 A; T <sub>j</sub> = 125 °C	-	-	-10	μA
I <sub>EBO</sub>	emitter-base cut-off current	V <sub>EB</sub> = -5 V; I <sub>C</sub> = 0 A; T <sub>amb</sub> = 25 °C	-	-	-50	nA
h <sub>FE</sub>	DC current gain	V <sub>CE</sub> = -10 V; I <sub>C</sub> = -0.1 mA; T <sub>amb</sub> = 25 °C	75	-	-	
		V <sub>CE</sub> = -10 V; I <sub>C</sub> = -1 mA; T <sub>amb</sub> = 25 °C	100	-	-	
		V <sub>CE</sub> = -10 V; I <sub>C</sub> = -10 mA; T <sub>amb</sub> = 25 °C	100	-	-	
		V <sub>CE</sub> = -10 V; I <sub>C</sub> = -150 mA; T <sub>amb</sub> = 25 °C	100	-	300	
		V <sub>CE</sub> = -10 V; I <sub>C</sub> = -500 mA; T <sub>amb</sub> = 25 °C	50	-	-	
V <sub>CEsat</sub>	collector-emitter saturation voltage	I <sub>C</sub> = -150 mA; I <sub>B</sub> = -15 mA; T <sub>amb</sub> = 25 °C	-	-	-400	mV
		I <sub>C</sub> = -500 mA; I <sub>B</sub> = -50 mA; T <sub>amb</sub> = 25 °C	-	-	-1.6	V
V <sub>BEsat</sub>	base-emitter saturation voltage	I <sub>C</sub> = -150 mA; I <sub>B</sub> = -15 mA; T <sub>amb</sub> = 25 °C	-	-	-1.3	V
		I <sub>C</sub> = -500 mA; I <sub>B</sub> = -50 mA; T <sub>amb</sub> = 25 °C	-	-	-2.6	V
t <sub>d</sub>	delay time	I <sub>C</sub> = -150 mA; I <sub>Bon</sub> = -15 mA; I <sub>Boff</sub> = 15 mA; T <sub>amb</sub> = 25 °C	-	-	12	ns
t <sub>r</sub>	rise time		-	-	30	ns
t <sub>on</sub>	turn-on time		-	-	40	ns
t <sub>s</sub>	storage time		-	-	300	ns
t <sub>f</sub>	fall time		-	-	65	ns
t <sub>off</sub>	turn-off time		-	-	365	ns
C <sub>C</sub>	collector capacitance		V <sub>CB</sub> = -10 V; I <sub>E</sub> = 0 A; i <sub>e</sub> = 0 A; f = 1 MHz; T <sub>amb</sub> = 25 °C	-	-	8
C <sub>E</sub>	emitter capacitance	V <sub>EB</sub> = -2 V; I <sub>C</sub> = 0 A; i <sub>c</sub> = 0 A; f = 1 MHz; T <sub>amb</sub> = 25 °C	-	-	30	pF
f <sub>T</sub>	transition frequency	V <sub>CE</sub> = -20 V; I <sub>C</sub> = -50 mA; f = 100 MHz; T <sub>amb</sub> = 25 °C	200	-	-	MHz



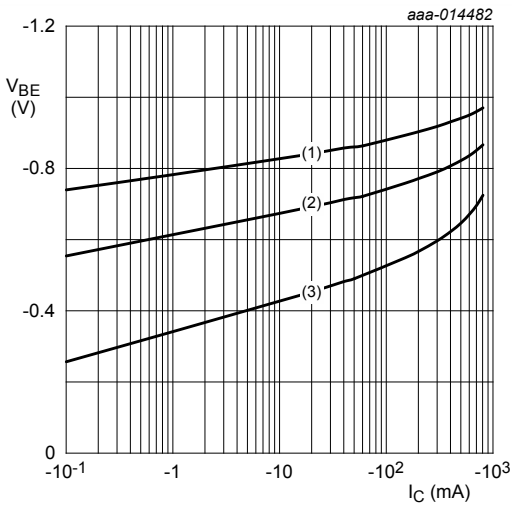
$V_{CE} = -10\text{ V}$   
 (1)  $T_{amb} = 150^\circ\text{C}$   
 (2)  $T_{amb} = 25^\circ\text{C}$   
 (3)  $T_{amb} = -55^\circ\text{C}$

**Fig. 3. DC current gain as a function of collector current; typical values**



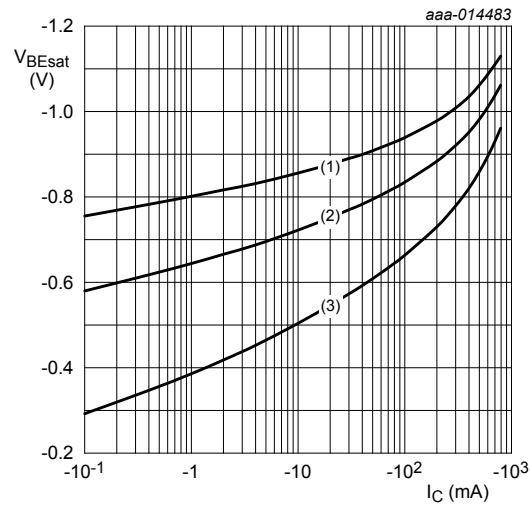
$T_{amb} = 25^\circ\text{C}$

**Fig. 4. Collector current as a function of collector-emitter voltage; typical values**



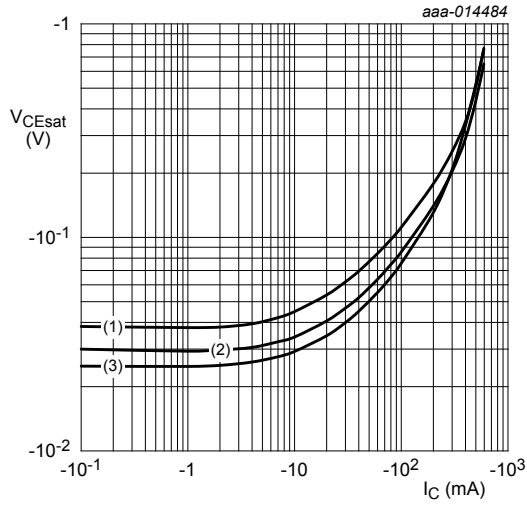
$V_{CE} = -10\text{ V}$   
 (1)  $T_{amb} = -55^\circ\text{C}$   
 (2)  $T_{amb} = 25^\circ\text{C}$   
 (3)  $T_{amb} = 150^\circ\text{C}$

**Fig. 5. Base-emitter voltage as a function of collector current; typical values**



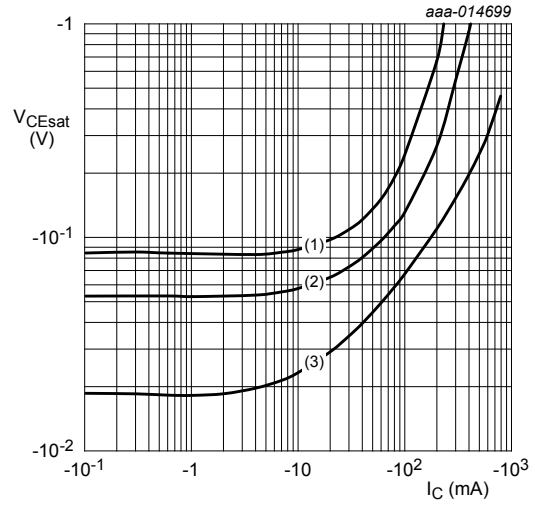
$I_C/I_B = 10$   
 (1)  $T_{amb} = -55^\circ\text{C}$   
 (2)  $T_{amb} = 25^\circ\text{C}$   
 (3)  $T_{amb} = 150^\circ\text{C}$

**Fig. 6. Base-emitter saturation voltage as a function of collector current; typical values**



$I_C/I_B = 20$   
 (1)  $T_{amb} = 150\text{ °C}$   
 (2)  $T_{amb} = 25\text{ °C}$   
 (3)  $T_{amb} = -55\text{ °C}$

**Fig. 7. Collector-emitter saturation voltage as a function of collector current; typical values**



$T_{amb} = 25\text{ °C}$   
 (1)  $I_C/I_B = 100$   
 (2)  $I_C/I_B = 50$   
 (3)  $I_C/I_B = 10$

**Fig. 8. Collector-emitter saturation voltage as a function of collector current; typical values**

### 11. Test information

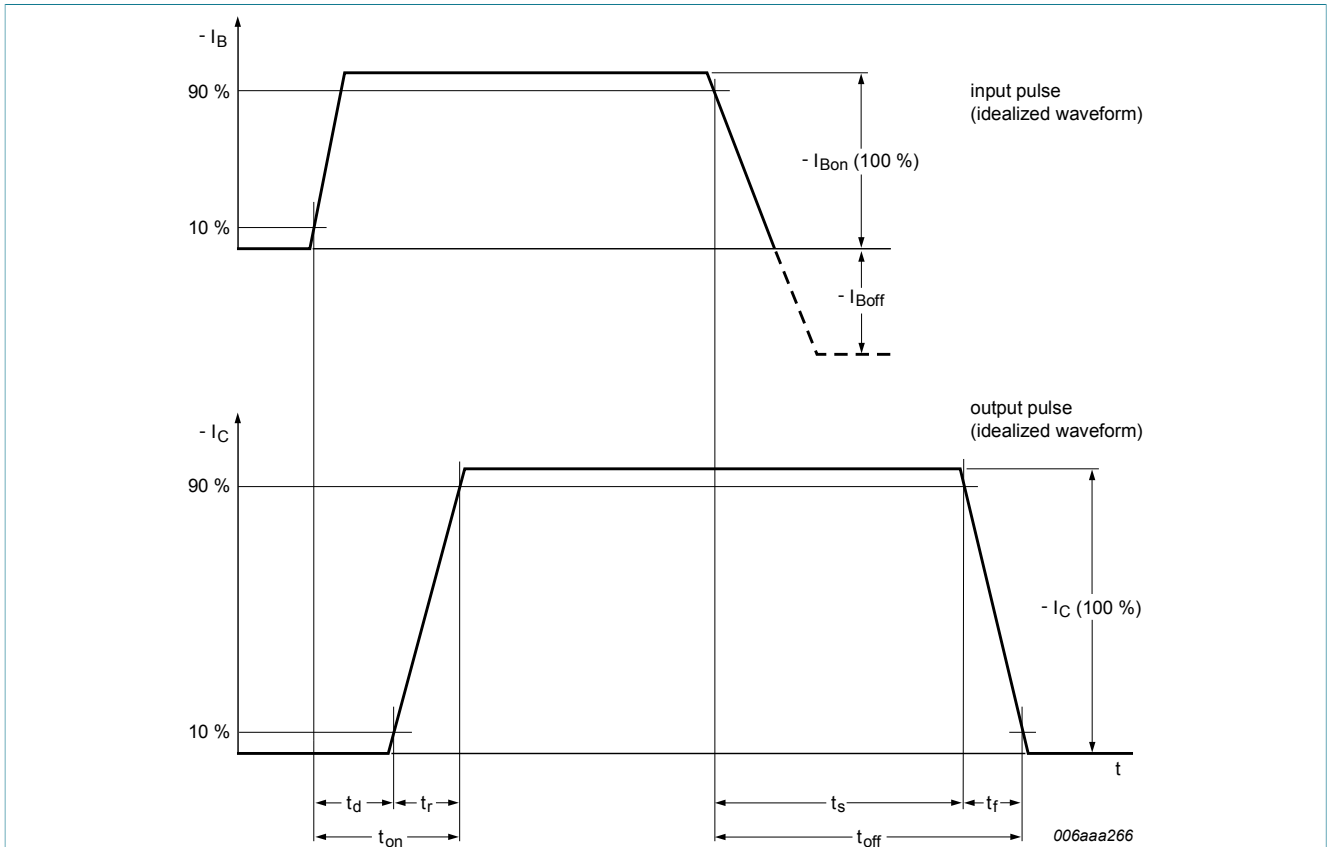


Fig. 9. BISS transistor switching time definition

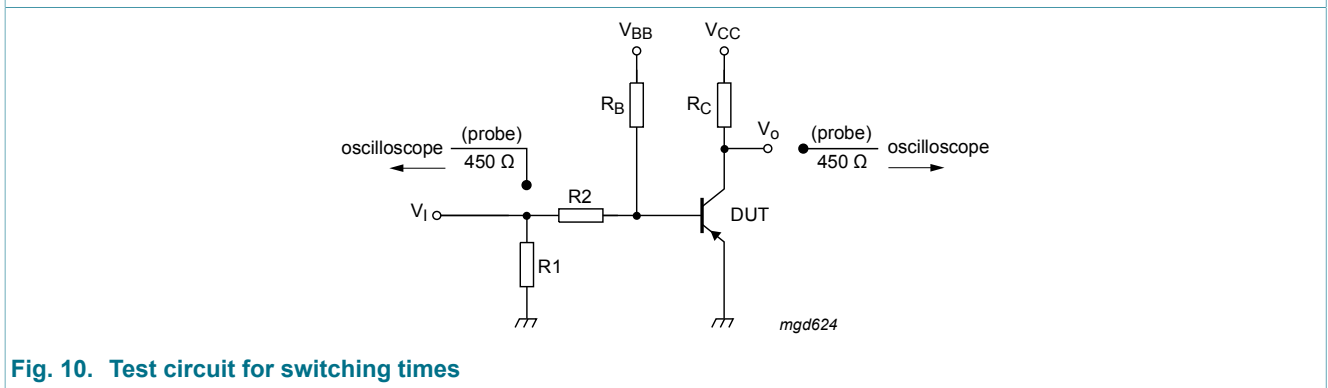


Fig. 10. Test circuit for switching times

#### 11.1 Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard Q101 - *Stress test qualification for discrete semiconductors*, and is suitable for use in automotive applications.



## 12. Package outline

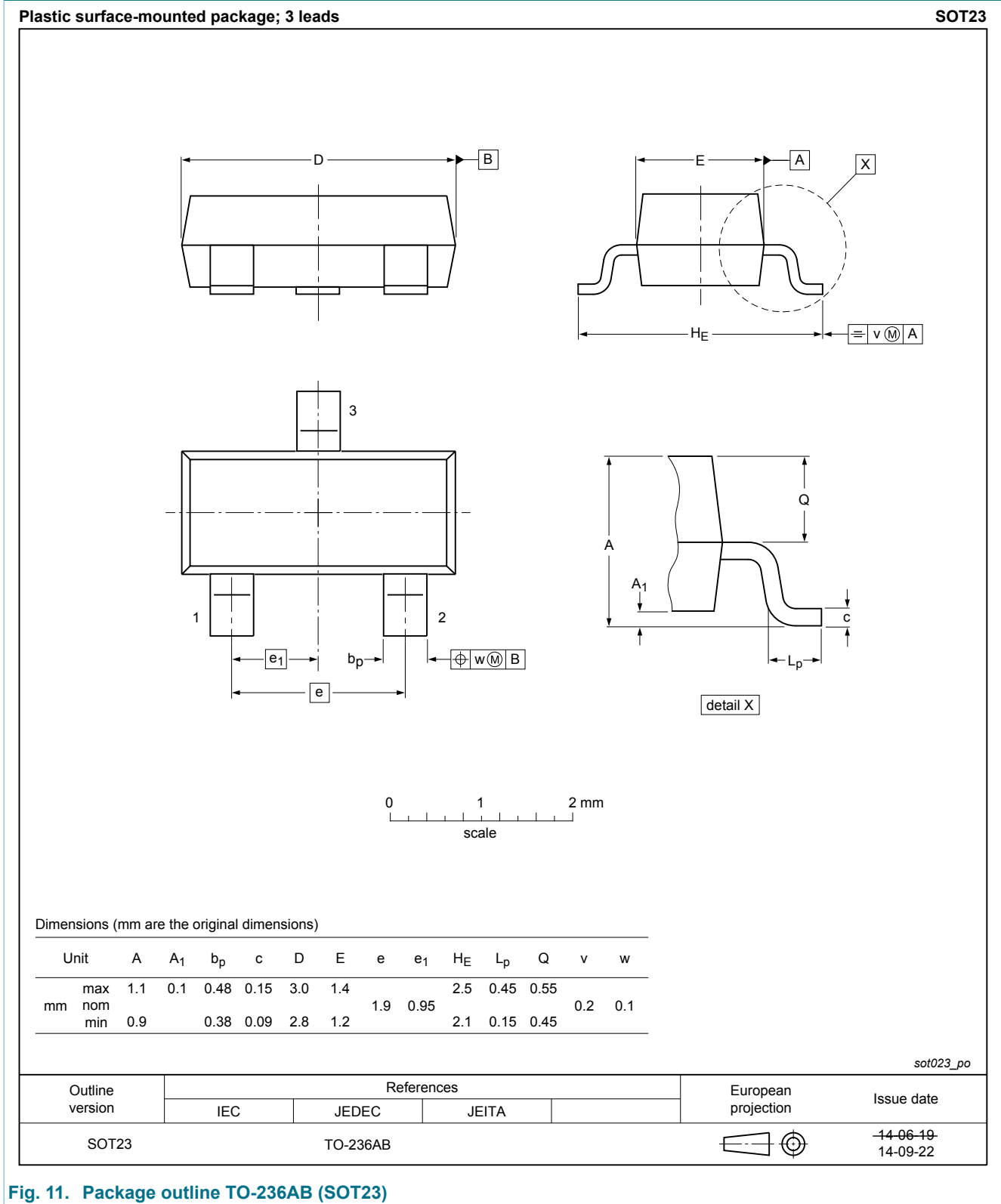


Fig. 11. Package outline TO-236AB (SOT23)

### 13. Soldering

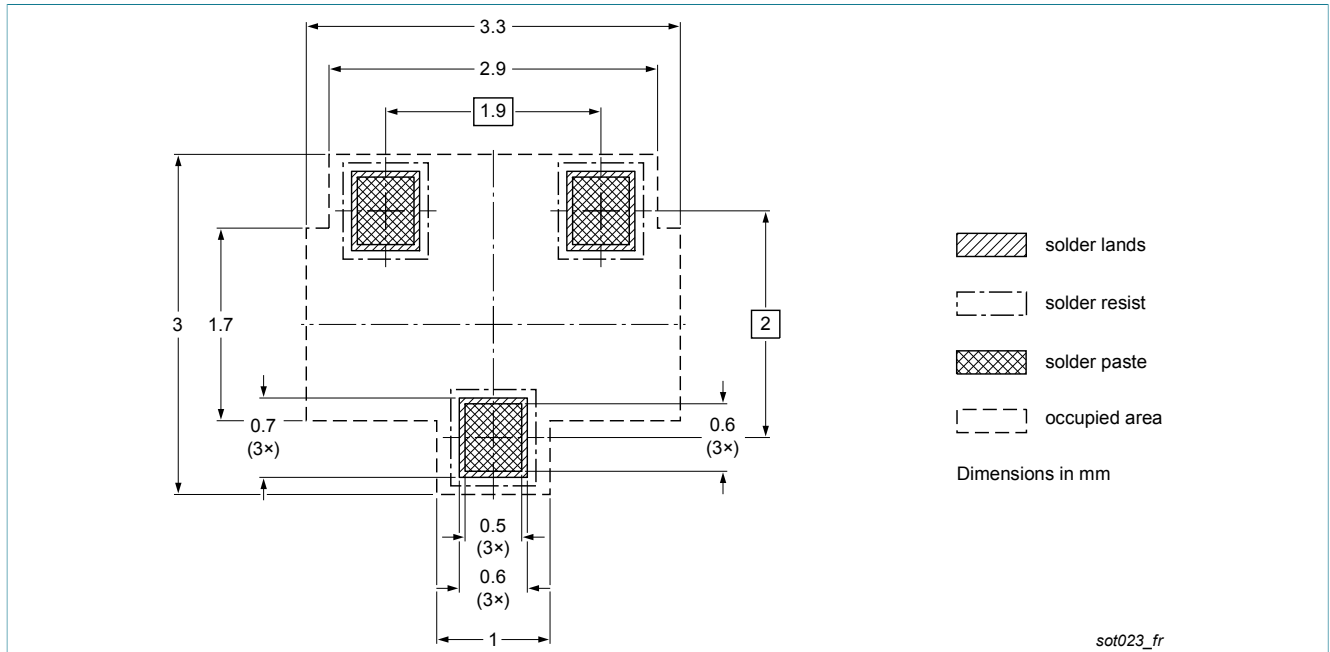


Fig. 12. Reflow soldering footprint for TO-236AB (SOT23)

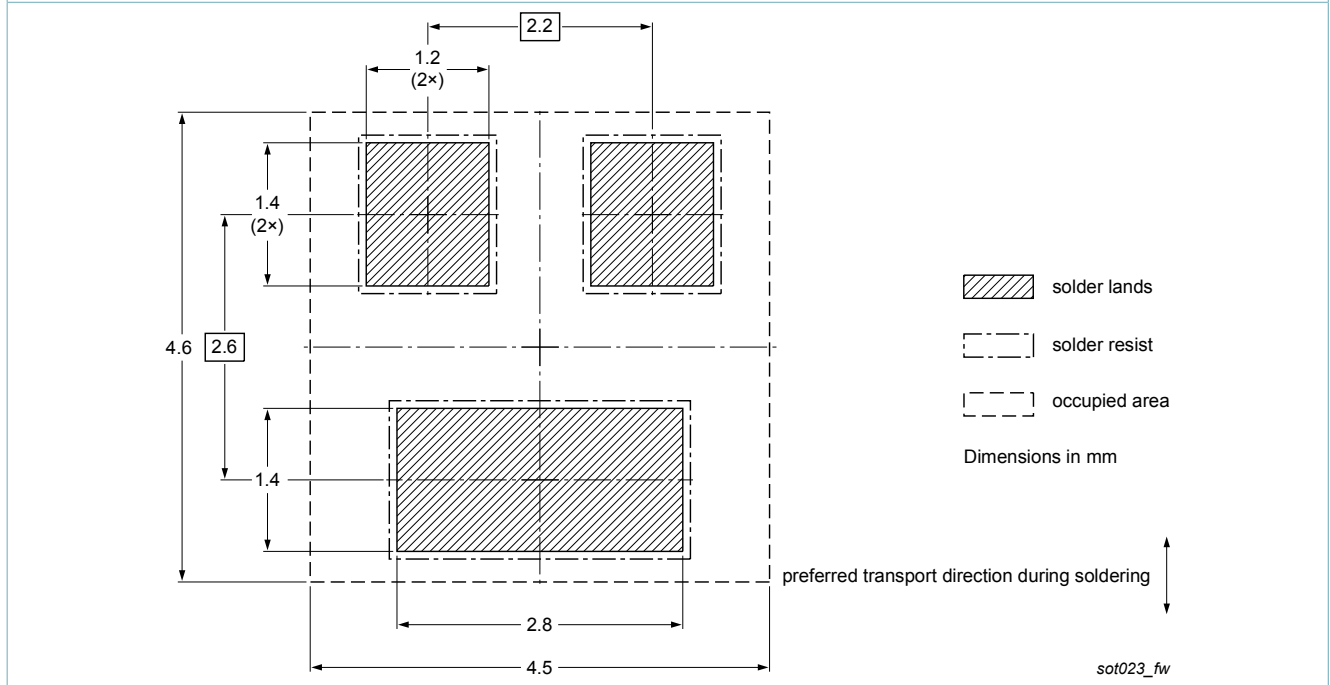


Fig. 13. Wave soldering footprint for TO-236AB (SOT23)

## 14. Revision history

Table 8. Revision history

Data sheet ID	Release date	Data sheet status	Change notice	Supersedes
PMBT2907A v.5	20150306	Product data sheet	-	PMBT2907_ PMBT2907A v.4
Modifications:	<ul style="list-style-type: none"> <li>The format of this data sheet has been redesigned to comply with the new identity guidelines of NXP Semiconductors</li> <li>Legal texts have been adapted to the new company name where appropriate</li> <li>Data sheet PMBT29007_PMBT2907A split into two separate data sheets</li> </ul>			
PMBT2907_ PMBT2907A v.4	20040116	Product data sheet	-	PMBT2907_ PMBT2907A v.3
PMBT2907_ PMBT2907A v.3	19990427	Product specification	-	PMBT2907_ PMBT2907A v.2
PMBT2907_ PMBT2907A v.2	19970904	Product specification	-	PMBT2907_ PMBT2907A v.1
PMBT2907_ PMBT2907A v.1	19970507	Product specification	-	-

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Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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## 16. Contents

1	General description .....	1
2	Features and benefits .....	1
3	Applications .....	1
4	Quick reference data .....	1
5	Pinning information .....	1
6	Ordering information .....	2
7	Marking .....	2
8	Limiting values .....	3
9	Thermal characteristics .....	3
10	Characteristics .....	5
11	Test information .....	8
11.1	Quality information .....	8
12	Package outline .....	9
13	Soldering .....	10
14	Revision history .....	11
15	Legal information .....	12
15.1	Data sheet status .....	12
15.2	Definitions .....	12
15.3	Disclaimers .....	12
15.4	Trademarks .....	13

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